

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
CHING-BAI HWANG	06/05/2007
JIE ZHANG	06/05/2007
RAN LIN	06/05/2007
RECEIVING PARTY DATA	
Name:	Foxconn Technology Co., Ltd.
Street Address:	3-2,CHUNG SHAN ROAD
City:	Tu-Cheng,Taipei Hsien
State/Country:	TAIWAN
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	29280926
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ATTORNEY DOCKET NUMBER:	US14518
NAME OF SUBMITTER:	Frank R. Niranjan
Total Attachments: 2 source=US14518070607ASM#page1.tif source=US14518070607ASM#page2.tif	

CH \$40.00 29280926

ASSIGNMENT

In consideration of value received, the receipt and sufficiency of which are hereby acknowledged, the undersigned ASSIGNOR(S)

- | | | | |
|----|------------------------|---------------|-----------------------------------|
| 1. | <u>Ching-Bai Hwang</u> | , residing at | <u>Tu-Cheng, Taipei, Taiwan</u> |
| 2. | <u>Jie Zhang</u> | , residing at | <u>Shenzhen, Guangdong, China</u> |
| 3. | <u>Ran Lin</u> | , residing at | <u>Shenzhen, Guangdong, China</u> |
| 4. | _____ | , residing at | _____ |
| 5. | _____ | , residing at | _____ |
| 6. | _____ | , residing at | _____ |
| 7. | _____ | , residing at | _____ |
| 8. | _____ | , residing at | _____ |

hereby sell(s), assign(s) and transfer(s) unto: Foxconn Technology Co.,Ltd, having a principal place of business at 3-2, Chung Shan Road, Tu-cheng City, Taipei Hsien, Taiwan, R.O.C. hereafter designated "ASSIGNEE" the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100, in the invention and all patent applications including any and all divisions, continuations, substitutes, and reissues thereof, and all resulting patents, known as THERMAL MODULE for which the undersigned

[] previously executed --- Ser. No. _____ and filing date of _____
[x] is executing concurrently herewith

an application for Letters Patent of United States of America

AND the undersigned hereby authorize(s) and request(s) the United States Commissioner of Patents and Trademarks to issue said Letters Patent to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agree(s) that the attorneys of record in said application, if any, shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agree(s) to testify and execute any papers for ASSIGNEE, its successors, assigns and legal representatives, deemed essential by ASSIGNEE to ASSIGNEE's full protection and title in and to the invention hereby transferred.

1. Ching-Bai Hwang Jun. 5, 2007
Ching-Bai Hwang inventor Date Witness

2. Jie Zhang Jun. 5, 2007
Jie Zhang inventor Date Witness

3. Ran Lin Jun. 5, 2007
Ran Lin inventor Date Witness

4. _____
inventor Date Witness

5. _____
inventor Date Witness

6. _____
inventor Date Witness

7. _____
inventor Date Witness

8. _____
inventor Date Witness